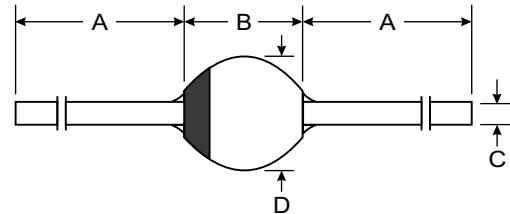


### Features

- Hermetically Sealed Glass Body Construction
- Controlled Avalanche Characteristics
- Super-Fast Switching for High Efficiency
- High Current Capability and Low Forward Voltage Drop
- Surge Overload Rating to 90A Peak
- Low Reverse Leakage Current



### Mechanical Data

- Case: SOD-64, Glass
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 1.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

SOD-64		
Dim	Min	Max
A	26.0	—
B	—	4.2
C	—	1.35
D	—	4.3
All Dimensions in mm		

### Maximum Ratings and Electrical Characteristics @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	BYV28/50	BYV28/100	BYV28/150	BYV28/200	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	50	100	150	200	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	100	140	V
Non-Repetitive Peak Reverse Voltage	$V_{RSM}$	55	110	165	220	V
Average Rectified Output Current (Note 1)	$I_O$	3.5				A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	90				A
Repetitive Forward Surge Current	$I_{FRM}$	25				A
Forward Voltage @ $I_F = 5.0\text{A}$	$V_{FM}$	1.1				V
Peak Reverse Current @ $T_j = 25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_j = 165^\circ\text{C}$	$I_{RM}$	1.0 150				$\mu\text{A}$
Non-Repetitive Reverse Avalanche Energy $I_R = 0.6\text{A}$ Inductive Load @ $T_j = 175^\circ\text{C}$	$E_{RSM}$	20				mJ
Reverse Recovery Time (Note 2)	$t_{rr}$	30				ns
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	25				K/W
Operating and Storage Temperature Range	$T_j, T_{STG}$	-65 to +175				$^\circ\text{C}$

Notes: 1. Leads maintained at ambient temperature at a distance of 10mm from the case.  
2. Measured with  $I_F = 0.5\text{A}$ ,  $I_R = 1.0\text{A}$ ,  $t_{rr} = 0.25\mu\text{s}$ . See Figure 4.

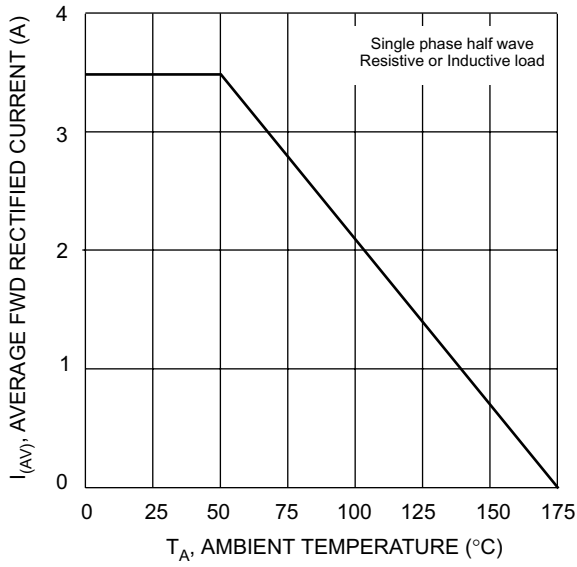


Fig. 1 Forward Current Derating Curve

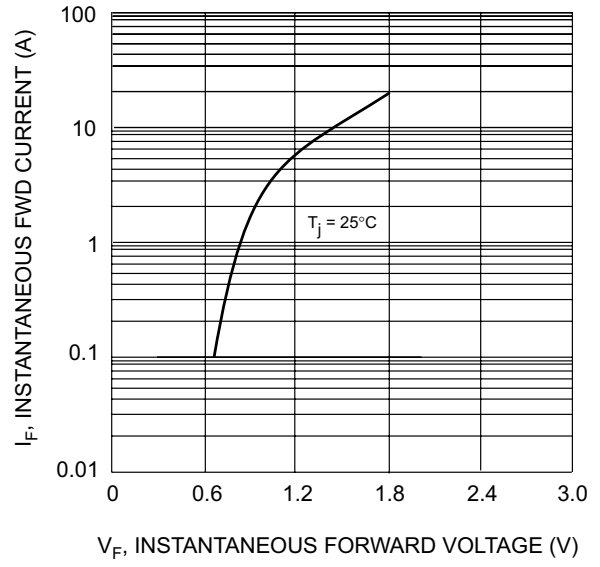


Fig. 2 Typical Forward Characteristics

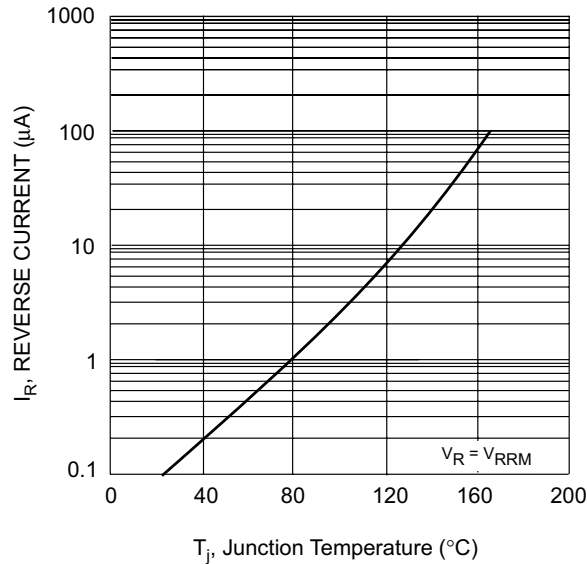


Fig. 3 Typical Reverse Characteristics

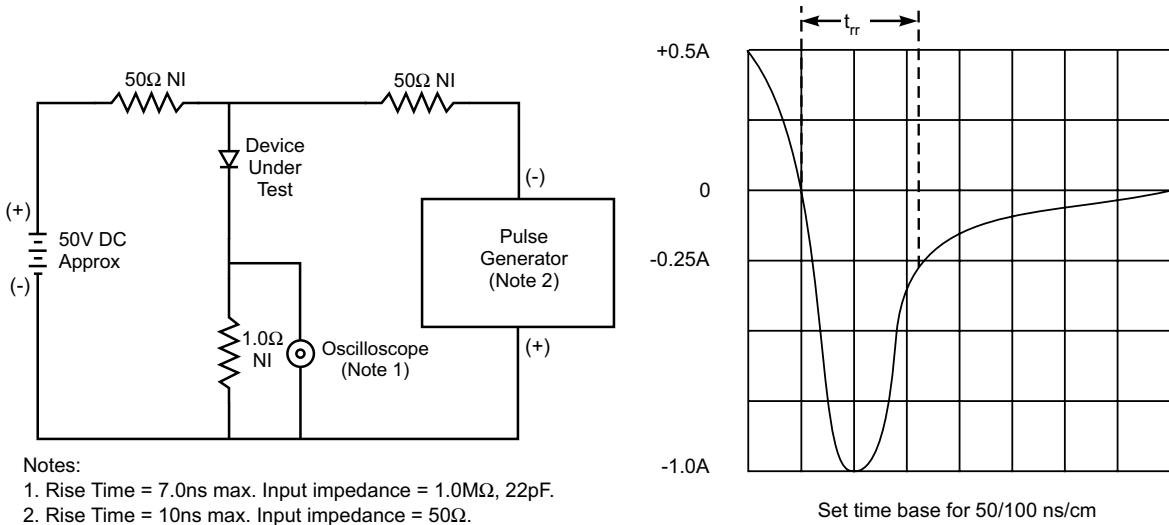


Fig. 4 Reverse Recovery Time Characteristic and Test Circuit